

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT6747521

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HYEONCHUL LEE	06/04/2021
KYOUNGHEE PARK	06/04/2021
KYUNGHWAN KIM	06/07/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	STATS CHIPPAK PTE. LTD.
<b>Street Address:</b>	5 YISHUN STREET 23
<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	768442
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17339210
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	480-499-9400
<b>Email:</b>	main@plgaz.com
<b>Correspondent Name:</b>	PATENT LAW GROUP: ATKINS AND ASSOCIATES
<b>Address Line 1:</b>	123 W. CHANDLER HEIGHTS ROAD, #12535
<b>Address Line 4:</b>	CHANDLER, ARIZONA 85248
<b>ATTORNEY DOCKET NUMBER:</b>	2515.0540
<b>NAME OF SUBMITTER:</b>	LISA ROSSETTI
<b>SIGNATURE:</b>	/Lisa Rossetti/
<b>DATE SIGNED:</b>	06/07/2021
<b>Total Attachments: 3</b>	
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source=17339210ASSIGNMENT#page3.tif	

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HYEONCHUL LEE of South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS CHIPPAC, PTE. LTD. (STATS CHIPPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR MANUFACTURING DEVICE TO SECURELY HOLD RECONSTITUTED PANELS FOR TRANSPORT AND MANUFACTURING PROCESSES, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0540, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

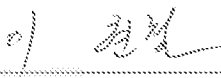
I hereby sell, assign, and transfer unto STATS CHIPPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS CHIPPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS CHIPPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS CHIPPAC, for the sole use and behalf of STATS CHIPPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS CHIPPAC in the same manner.

I agree that, when requested, I will, without charge to STATS CHIPPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS CHIPPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS CHIPPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

6/4 2021  
Date Signed

  
Signature for HYEONCHUL LEE

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYOUNGHEE PARK of South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS CHIPPAC, PTE. LTD. (STATS CHIPPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR MANUFACTURING DEVICE TO SECURELY HOLD RECONSTITUTED PANELS FOR TRANSPORT AND MANUFACTURING PROCESSES, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0540, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2021.06.04

Date Signed



Signature for KYOUNGHEE PARK

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYUNGHWAN KIM of South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS CHIPPAC, PTE. LTD. (STATS CHIPPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR MANUFACTURING DEVICE TO SECURELY HOLD RECONSTITUTED PANELS FOR TRANSPORT AND MANUFACTURING PROCESSES, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0540, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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21.06.07  
Date Signed

  
Signature for KYUNGHWAN KIM